

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT												
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT												
<b>CONVEYING PARTY DATA</b>													
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Ryuji Kohno</td> <td>11/11/2002</td> </tr> <tr> <td>Hideo Miura</td> <td>11/19/2002</td> </tr> <tr> <td>Masatoshi Kanamaru</td> <td>11/11/2002</td> </tr> <tr> <td>Hiroya Shimizu</td> <td>11/19/2002</td> </tr> <tr> <td>Hideyuki Aoki</td> <td>11/18/2002</td> </tr> </tbody> </table>		Name	Execution Date	Ryuji Kohno	11/11/2002	Hideo Miura	11/19/2002	Masatoshi Kanamaru	11/11/2002	Hiroya Shimizu	11/19/2002	Hideyuki Aoki	11/18/2002
Name	Execution Date												
Ryuji Kohno	11/11/2002												
Hideo Miura	11/19/2002												
Masatoshi Kanamaru	11/11/2002												
Hiroya Shimizu	11/19/2002												
Hideyuki Aoki	11/18/2002												
<b>RECEIVING PARTY DATA</b>													
<b>Name:</b>	HITACHI, LTD.												
<b>Street Address:</b>	6, Kanda Surugadai 4-chome, Chiyoda-ku												
<b>City:</b>	Tokyo												
<b>State/Country:</b>	JAPAN												
<b>PROPERTY NUMBERS Total: 1</b>													
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>10274422</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	10274422								
Property Type	Number												
Application Number:	10274422												
<b>CORRESPONDENCE DATA</b>													
<b>Fax Number:</b>	(650)326-2422												
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>													
<b>Phone:</b>	650-326-2400												
<b>Email:</b>	rl@townsend.com												
<b>Correspondent Name:</b>	TOWNSEND AND TOWNSEND AND CREW LLP												
<b>Address Line 1:</b>	Two Embarcadero Center, Eighth Floor												
<b>Address Line 4:</b>	San Francisco, CALIFORNIA 94111-3834												
<b>NAME OF SUBMITTER:</b>	Chun-Pok Leung												
<b>Total Attachments: 1</b> source=16869S-064000US Assignment#page1.tif													

CH \$40.00 10274422

W0693-01  
(\*)

ASSIGNMENT  
( 譲渡証 )

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

"METHOD OF MANUFACTURING A SEMICONDUCTOR DEVICE"

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Ryuzo Kohno</u>	<u>11/11/02</u>
2) <u>Hideaki Irima</u>	<u>11/19/02</u>
3) <u>Masatoshi Kanamaru</u>	<u>11/11/02</u>
4) <u>Hiroya Shimizu</u>	<u>11/19/02</u>
5) <u>Hideyuki Aoki</u>	<u>11/18/02</u>
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____